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Abstract of the Disclosure

In a semiconductor device, a semiconductor element is bonded to an insulating circuit board. A resin layer for bonding the 5 semiconductor element to the insulating circuit board is extended so as to become greater in size than the semiconductor element. Further, the surroundings of the semiconductor element are sealed with resin. Reliability of mounting is improved by alleviating stress developing in a solder joint of the external electrodes of the circuit board.

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